

MATERIALS & FINISHES

BODY: BRASS
PLATED GOLD

CONTACT: BERYLLIUM COPPER
PLATED GOLD

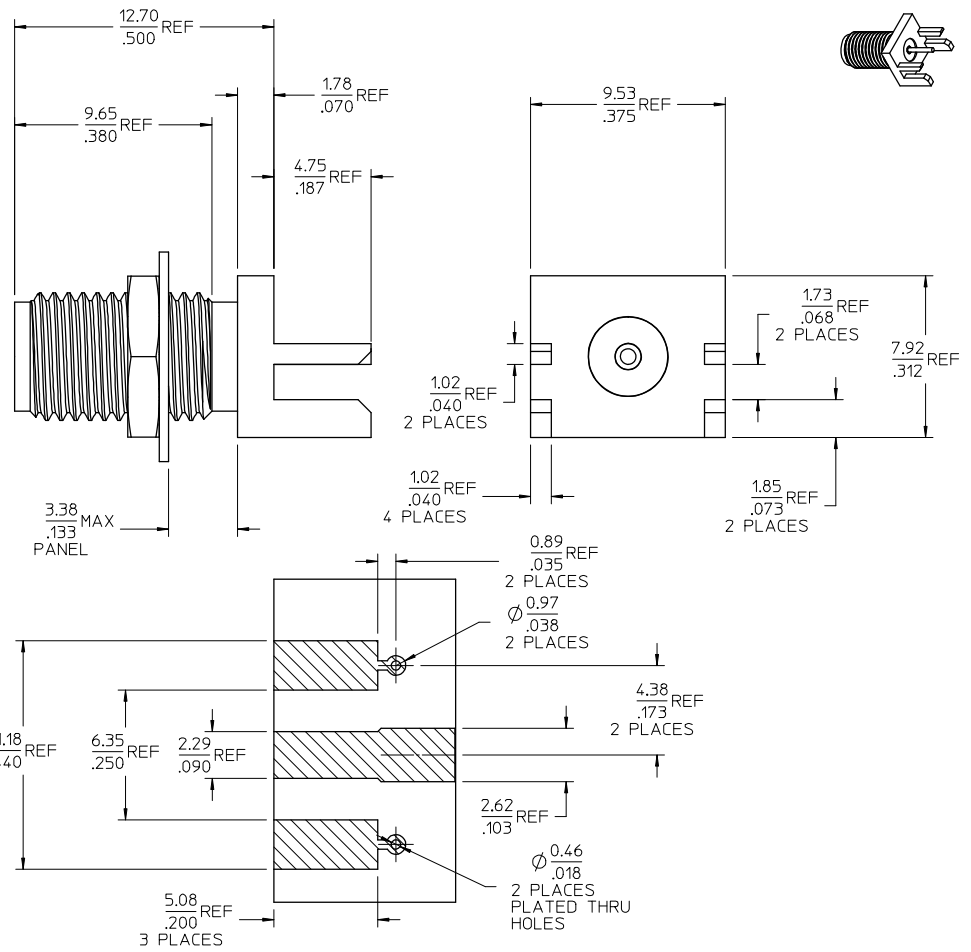
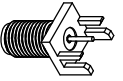
INSULATOR: TEFLON

JAM NUT: BRASS
PLATED GOLD

LOCK WASHER: PHOSPHOR BRONZE
PLATED GOLD

HARDWARE:

JAM NUT: 7.87/.310 HEX X 1.55/.061
LOCK WASHER: \varnothing 10.26/404 X \varnothing 6.65/262 X .46/018



RECOMMENDED PCB LAYOUT
BOARD THICKNESS 1.57/.062

PART # 73251-1290

MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: UPDATED VIEW OF REVISED BODY. EC NO: URF2008-0633 DRW: ARBERTSON 2008/06/11 CHK: SSS 2008/06/11 APPR: JWIENER 2008/06/11 A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$	4 PLACES ± .005 ± .005	MM/IN	METRIC	\odot	
	$\nabla=0$	3 PLACES ± .005 ± .005				
		2 PLACES ± .005 ± .005				
		1 PLACE ± .005 ± .005				
		ANGULAR ± 2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

DRAWN BY	DATE	TITLE
SSS	2000/08/00	SMA, JACK
CHECKED BY	DATE	EDGEMOUNT FOR .062 PCB
SSS	2000/08/00	SMA-J/PCB, EWR-2864
APPROVED BY	DATE	MOLEX INCORPORATED
GMH	2000/08/00	
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
732511290	SD-73251-129	1 OF 1
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